

The following Listing of Claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

1. (Currently Amended) An electronic circuit board intermediate member comprising:

a plurality of good interposer boards being selected and cut out from an interposer board tape or being selected and cut out from an interposer board tape excepting blank sections; and

a carrier tape being formed as an exfoliate layer,

the good interposer boards being disposed on the carrier tape at every predetermined interval, each good interposer board having a base member mounting an IC chip, extended electrodes being formed on the base member to be arranged between the carrier tape and the base member, the carrier tape being arranged only on a side of the extended electrode opposite the base member, each extended electrode being connected to a corresponding electrode of the IC chip, and an adhesive layer being formed to cover the extended electrode.

2. (Currently Amended) A manufacturing method for manufacturing an electronic circuit board intermediate member comprising:

applying adhesive on extended electrodes of an interposer board tape, the interposer board tape being obtained by forming the extended electrodes on a base member, a plurality of IC chips being mounted on the base member, and each of the extended electrodes being connected to corresponding electrode of each of the IC chips;

obtaining individual interposer boards by cutting the interposer board tape, and
selecting only good interposer boards; and

disposing only the interposer boards on a carrier tape at every predetermined interval,
the carrier tape being obtained by forming an exfoliate layer on a base tape such that the
extended electrodes are arranged between the carrier tape and the base member, the carrier
tape being arranged only on a side of the extended electrode opposite the base member.

3. (Currently Amended) A manufacturing apparatus for manufacturing an
electronic circuit board intermediate member comprising:

first means for applying adhesive on extended electrodes of an interposer board tape,
the interposer board tape being obtained by forming the extended electrodes on a base
member, a plurality of IC chips being mounted on the base member, and each of the extended
electrodes being connected to a corresponding electrode of each of the IC chips;

second means for obtaining individual interposer boards by cutting the interposer
board tape;

third means for selecting only good interposer boards; and

fourth means for disposing only the interposer boards on a carrier tape at every
predetermined interval, the carrier tape being obtained by forming an exfoliate layer on one
face of a base tape such that the extended electrodes are arranged between the carrier tape and
the base member, the carrier tape being arranged only on a side of the extended electrode
opposite the base member.

4. (Currently Amended) A manufacturing method for manufacturing non-contact ID card and the like comprising:

peeling an interposer board from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards on a carrier tape at every predetermined interval, the interposer board being obtained by mounting an IC chip, by forming extended electrodes each connected to a corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape such that the extended electrodes are arranged between the carrier tape and the base member, the carrier tape being arranged only on a side of the extended electrode opposite the base member; and

depressing the interposer board to an antenna circuit board tape to face antenna electrodes formed on an antenna circuit base material film and the extended electrodes.

5. (Currently Amended) A manufacturing apparatus for manufacturing non-contact ID card and the like comprising:

means for peeling an interposer board one by one from an electronic circuit board intermediate member, the electronic circuit board intermediate member being obtained by disposing interposer boards on a carrier tape at every predetermined interval, each interposer board being obtained by mounting an IC chip, by forming extended electrodes each connected to corresponding electrode of the IC chip, and by forming an adhesive layer to cover the extended electrodes, the carrier tape being obtained by forming an exfoliate layer on one face of a base tape such that the extended electrodes are arranged between the carrier

tape and the base member, the carrier tape being arranged only on a side of the extended electrode opposite the base member; and

means for depressing the interposer board to an antenna circuit board tape to face antenna electrodes formed on an antenna circuit base material film and the extended electrodes.

6. (Previously Presented) The electronic circuit board intermediate member according to claim 1, wherein
the adhesive layer contacts the extended electrodes and the carrier tape.
7. (New) The electronic circuit board intermediate member according to claim 1, wherein the IC chip is embedded in the base member.
8. (New) The electronic circuit board intermediate member according to claim 7, wherein the electrode of the IC chip is arranged between the IC chip and the extended electrode.
9. (New) The manufacturing method according to claim 2, wherein the IC chip is embedded in the base member.
10. (New) The manufacturing method according to claim 9, wherein the electrode of the IC chip is arranged between the IC chip and the extended electrode.

11. (New) The manufacturing apparatus according to claim 3, wherein the IC chip is embedded in the base member.

12. (New) The manufacturing apparatus according to claim 11, wherein the electrode of the IC chip is arranged between the IC chip and the extended electrode.

13. (New) The manufacturing method according to claim 4, wherein the IC chip is embedded in the base member.

14. (New) The electronic circuit board intermediate member according to claim 13, wherein the electrode of the IC chip is arranged between the IC chip and the extended electrode.

15. (New) The manufacturing apparatus according to claim 5, wherein the IC chip is embedded in the base member.

16. (New) The manufacturing apparatus according to claim 15, wherein the electrode of the IC chip is arranged between the IC chip and the extended electrode.